

235-3019-01-0602

235-3019-01-0602 Information

Q	Heisener.com	Part Number Manufacturer Category Description Package	235-3019-01-0602 3M Connectors, Interconnects Sockets for ICs, Transistors CONN ZIG-ZAG ZIF 35POS GOLD - For the pricing/inventory/lead time, please contact	
F	For Reference Only		us Website: https://www.heisener.com E-mail: salesdept@heisener.com	Request a Quote

Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



235-3019-01-0602 Specifications

Manufacturer3MCategoryConnectors, InterconnectsBackageSockets for ICs, TransistorsPackage-SeriesTextool?TypeZig-Zag, ZIF (ZIP)Number of Positions or Pins (Grid)35 (1 x 17, 1 x 18)Pich - Mating0.050" (1.27mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperPich - PostClosed FramePich - PostSolderContact Finish - PostGoldContact Finish - PostSpin (0.76µm)Contact Material - PostBeryllium CopperHousing MaterialPolysulfone (PSU), Glass Filled	•	
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Housing MaterialPolysulfone (PSU), Glass FilledOperating Temperature-55°C ~ 125°C	Contact Finish Thickness - Post	30µin (0.76µm)
Operating Temperature -55°C ~ 125°C	Contact Material - Post	Beryllium Copper
	Housing Material	Polysulfone (PSU), Glass Filled
Report errors?	Operating Temperature	-55°C ~ 125°C
		Report errors?

235-3019-01-0602 Guarantees



Quality Guarantees

We provide 90 days warranty. * If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

SERVICE

Service Guarantees

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

235-3019-01-0602 Payment Methods





If you have any question about 235-3019-01-0602, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com